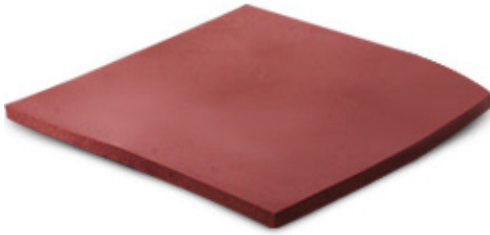


PC94

Non-Silicone Thermal Conductive Pad



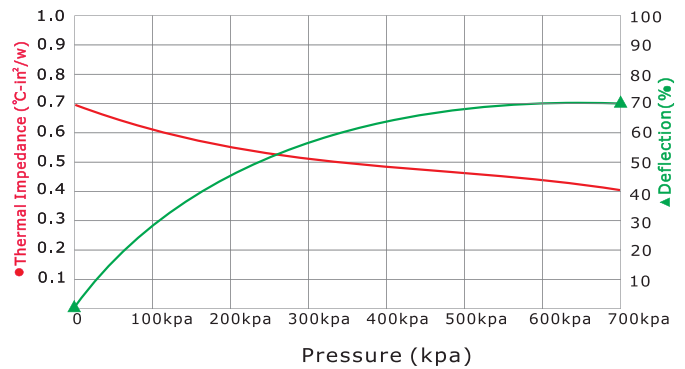
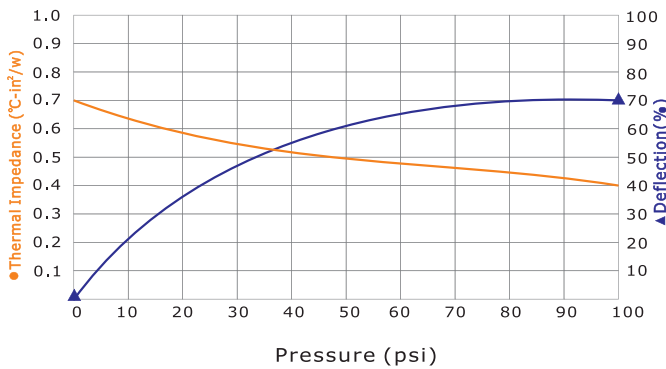
Features

- Low contact thermal impedance
- Good thermal conductivity
- Silicone free
- Long term stability

Applications

- Electronic components: IC / CPU / MOS
- LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc....
- DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection

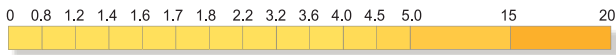


Properties

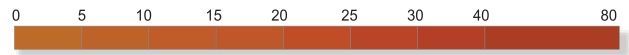
- REACH Compliant
- RoHS Compliant

Thermal Conductivity: 4 W/m.k
(W / m.k - Z Axis)

Hardness: 60 (Shore 00)
(Shore 00)



Testing sample thickness : 1.0 mm



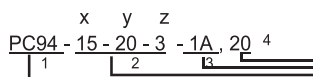
In "Thermal resistance V.S. Pressure V.S. Deflection" chart, PC94 provide low thermal impedance. The pressure gets higher the thermal impedance gets lower, and deflection percentage gets higher. PC94 provide good compliance and softness.

Property	PC94	Unit	Tolerance	Test Method
Colour	Red	-	-	Visual
Thickness (The thickness can be ordered)	0.25 / 5.0	mm	-	ASTM D374
	0.0098 / 0.1969	inch	-	ASTM D374
Thermal Conductivity	4	W/m.k	-	ASTM D5470
Flame Rating	V-1	-	-	UL 94
Dielectric Breakdown Voltage	10	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	2.5	g/cm ³	±0.2	ASTM D792
Working Temperature	-40~ 105	°C	-	-
Volume Resistance	>10 ¹⁰	Ohm-cm	-	ASTM D257
Elongation	100	%	±13	ASTM D412
Tensile Strength	2	Kgf/cm ²	±2	ASTM D412
Standard Shape	-	Sheet ones	-	-
Hardness	60	Shore 00	±5	ASTM D2240

Need samples?

Available to apply adhesive

Pre-cut different shape



1. Choose the P/N
2. Fill into size: x,y,z
3. Apply the adhesive or not? 0=none, 1A= one side, 2A= two sides
4. Fill the quantity you need